REMARKS

Claims 1-9 and 18 are cancelled, claim 10 is amended, and claims 10-17 and 19-37 are pending in the application. The amendment to claim 10 comprises incorporation of the subject matter of previous claim 18 into claim 10, and therefore does not introduce "new matter" into claim 10. Applicant requests substantive examination of the pending claims.

Respectfully submitted,

Dated: MARCH 6, 2002

By: _____
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Inventor ..... Chris Parfeniuk et al.
Assignee ..... Honeywell International Inc.
Group Art Unit 2823
Examiner ..... D. Collins
Attorney's Docket No. ..... 30-5016-(4015)
Title: Methods of Bonding Physical Vapor Deposition Target Materials to Backing Plate Materials

VERSION WITH MARKINGS TO SHOW CHANGES MADE ACCOMPANYING SUPPLEMENTAL AMENDMENT

In the Specification

The replacement specification paragraphs incorporate the following amendments. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

The title has been amended as follows:

~~Methods of Bonding First and Second Masses to One Another, and~~ Methods of Bonding Physical Vapor Deposition Target Materials to Backing Plate Materials

In the Claims

The claims have been amended as follows. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

Cancel claims 1-9 and 18.

10. (amended) A method of bonding a physical vapor deposition target material to a backing plate material, comprising:

joining the target material and backing plate material in physical contact with one

another, the backing plate and target material both predominately comprising aluminum; and

thermally treating the joined target and backing plate materials to simultaneously diffusion bond the target material to the backing plate material and develop grains in the target material, the diffusion bonding comprising solid state diffusion between the backing plate and target materials, a predominate portion of the developed grains having a maximum dimension of less than 100 microns.